## Nch 30V 390A Power MOSFET

V <sub>DSS</sub>	30V
R <sub>DS(on)</sub> (Max.)	0.67mΩ
I <sub>D</sub>	±390A
$P_D$	180W

# ● Features

- 1) Low on resistance
- 2) High power package (DFN5060T8LSHAAE)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen free
- 5) 100% Rg and UIS tested

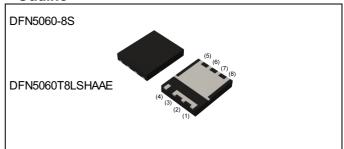
# Application

Switching

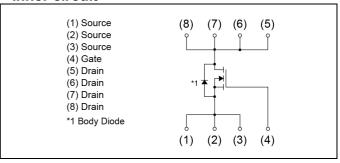
Motor drives

DC/DC converter

## Outline



## •Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	300
Туре	Tape width (mm)	12
	Quantity (pcs)	2500
	Taping code	TB1
	Marking	RS7E200BG

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Para	meter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	30	V	
Continuous dusin summent	Silicon limit (V <sub>GS</sub> =10V)	I <sub>D</sub> *1	±390	А
Continuous drain current	$T_c = 25^{\circ}C (V_{GS} = 10V)$	I <sub>D</sub> *2	±200	Α
Pulsed drain current	I <sub>DP</sub> *3	±900	Α	
Gate - Source voltage	$V_{GSS}$	±20	V	
Avalanche current, single p	I <sub>AS</sub> *4	30	Α	
Avalanche energy, single p	ulse	E <sub>AS</sub> *4	637	mJ
		P <sub>D</sub> *2	180	W
Power dissipation		P <sub>D</sub> *5	3.0	W
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and stor	T <sub>stg</sub>	-55 to +150	°C	

# ●Thermal resistance

Doromotor	Cymphal	Values			l limit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *2	-	-	0.69	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *5	-	-	41.7	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davanastan	Cymaele ed	Conditions		Values		Limit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		30	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_i} I_D = 1 \text{mA}$ referenced to 25°C		25.8	-	mV/°C
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	-	-	5	μA
Gate - Source leakage current	I <sub>GSS</sub>	$I_{GSS}$ $V_{GS} = \pm 20V, V_{DS} = 0V$		1	±500	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 1mA$	1.0	-	2.5	V
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-4.5	-	mV/°C
Static drain - source	D *6	V <sub>GS</sub> = 10V, I <sub>D</sub> = 50A	-	0.53	0.67	O
on - state resistance	R <sub>DS(on)</sub> *6	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 50A	-	0.75	1.06	mΩ
Gate resistance	$R_{G}$	-	-	0.6	-	Ω
Forward Transfer Admittance	Y <sub>fs</sub>  *6	V <sub>DS</sub> = 5V, I <sub>D</sub> = 50A	70	-	-	S

<sup>\*1</sup> Limited by silicon chip capability.

<sup>\*2</sup>  $T_c$ =25°C, Limited only by maximum temperature allowed.

<sup>\*3</sup> Pw  $\leq$  10 $\mu$ s , Duty cycle  $\leq$  1%

<sup>\*4</sup> L  $\simeq$  1mH, V<sub>DD</sub> = 15V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*5</sup> Mounted on a Cu board (40×40×0.8mm)

<sup>\*6</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davanastan	Cy made al	Canditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Onit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	9500	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15V	-	4390	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	550	-	
Turn - on delay time	t <sub>d(on)</sub> *6	$V_{DD} \simeq 15V, V_{GS} = 10V$	-	49	-	
Rise time	<b>t</b> <sub>r</sub> *6	I <sub>D</sub> = 50A	-	40	-	
Turn - off delay time	t <sub>d(off)</sub> *6	$R_L \simeq 0.3\Omega$	-	220	-	ns
Fall time	<b>t</b> <sub>f</sub> *6	$R_G = 10\Omega$	-	155	-	

# ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Doromotor	Cymahal	Conditions		Values			1.124
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate charge	O *6		V <sub>GS</sub> = 10V	-	135.0	-	
Total gate charge	Q <sub>g</sub> *6	V <sub>DD</sub> ≃ 15V		-	60.0	-	<b>"</b> C
Gate - Source charge	Q <sub>gs</sub> *6	I <sub>D</sub> = 50A	V <sub>GS</sub> = 4.5V	-	25.0	-	nC
Gate - Drain charge	Q <sub>gd</sub> *6			-	14.2	-	

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol Conditions			Unit		
raiametei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub> *2		1	-	150	Α
Pulse forward current	I <sub>SP</sub> *3	-	-	-	900	Α
Forward voltage	V <sub>SD</sub> *6	$V_{GS} = 0V, I_{S} = 50A$	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub> *6	I <sub>S</sub> = 50A, V <sub>GS</sub> =0V	-	86	-	ns
Reverse recovery charge	Q <sub>rr</sub> *6	di/dt = 100A/μs	-	50	-	nC

Fig.1 Power Dissipation Derating Curve

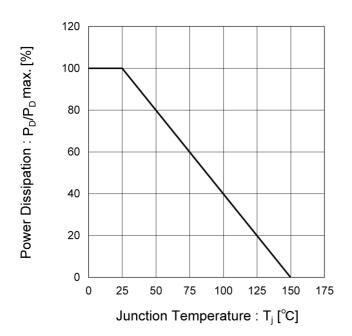
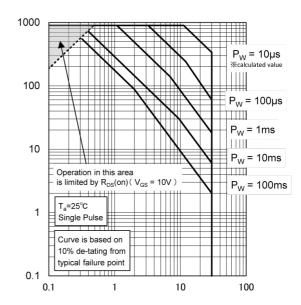


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage: V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

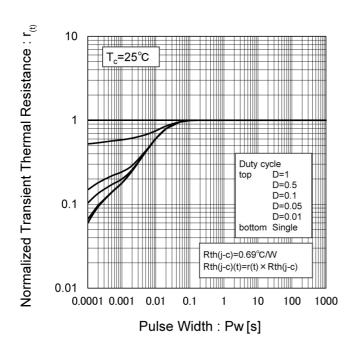


Fig.4 Single Pulse Maximum Power Dissipation

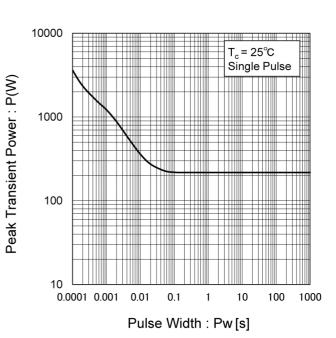


Fig.5 Typical Output Characteristics(I)

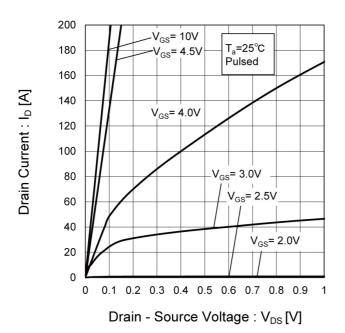
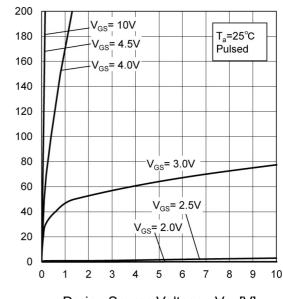


Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Breakdown Voltage vs.

Junction Temperature

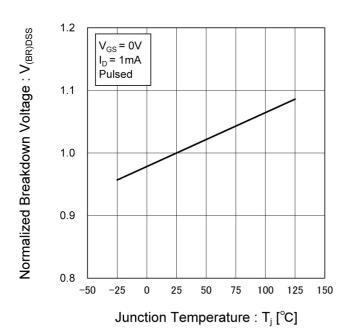
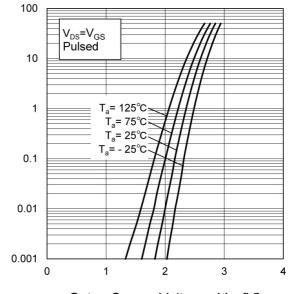


Fig.8 Typical Transfer Characteristics



Gate - Source Voltage : V<sub>GS</sub> [V]

Drain Current : I<sub>D</sub> [A]

Fig.9 Gate Threshold Voltage vs.
Junction Temperature

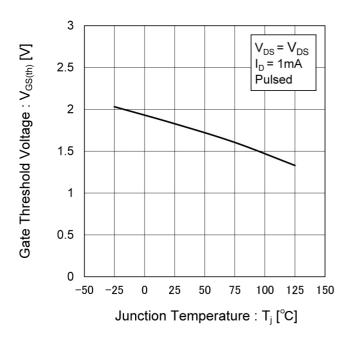


Fig.10 Forward Transfer Admittance vs.
Drain Current

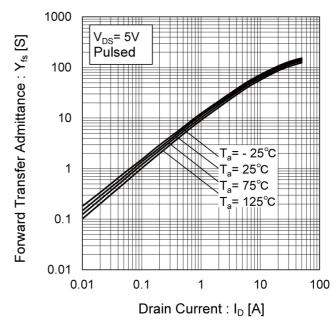


Fig.11 Drain Current Derating Curve

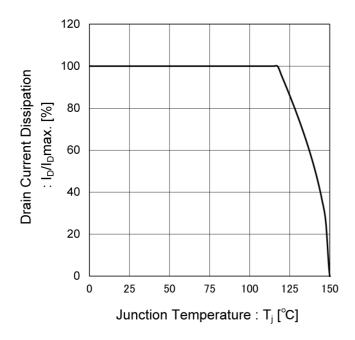


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

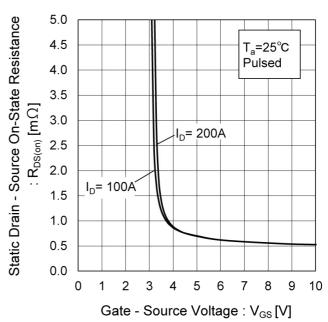


Fig.13 Static Drain - Source On - State
Resistance vs. Junction Temperature

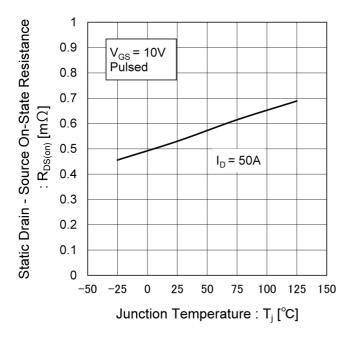


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

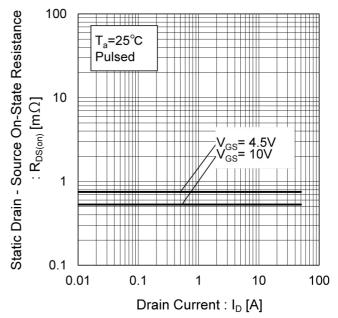


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

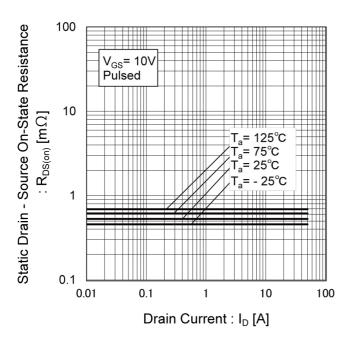


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

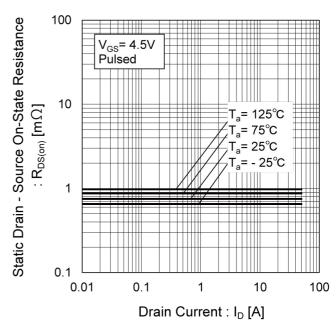


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

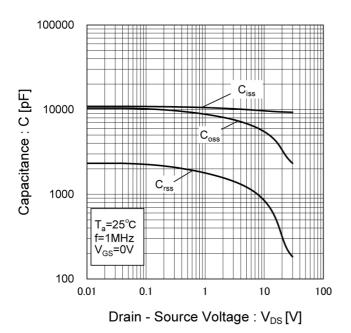


Fig.18 Switching Characteristics

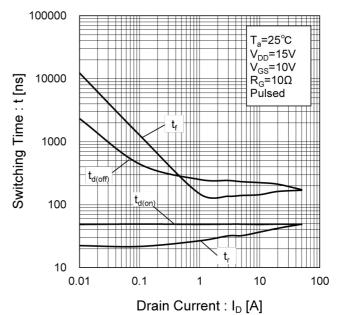


Fig.19 Typical Gate Charge

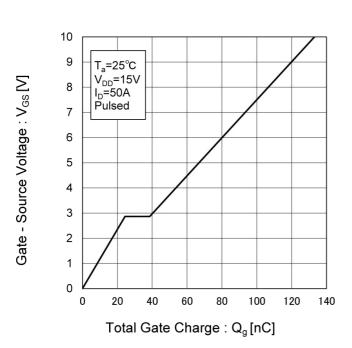
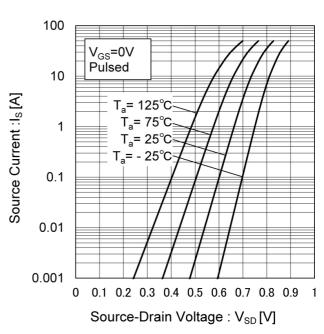


Fig.20 Source Current vs.

Source Drain Voltage



## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

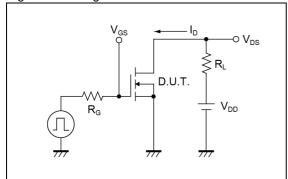


Fig.1-2 Switching Waveforms

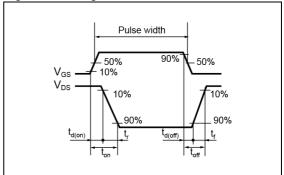


Fig.2-1 Gate Charge Measurement Circuit

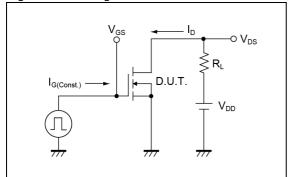


Fig.2-2 Gate Charge Waveform

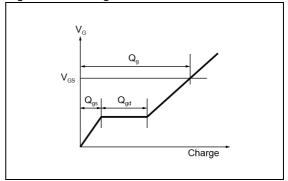


Fig.3-1 Avalanche Measurement Circuit

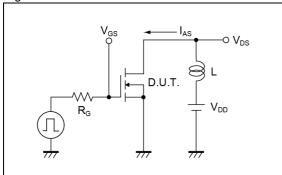
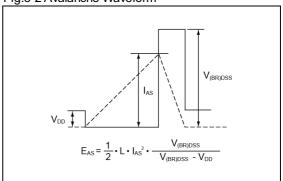


Fig.3-2 Avalanche Waveform



#### Notice

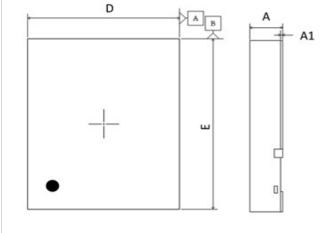
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

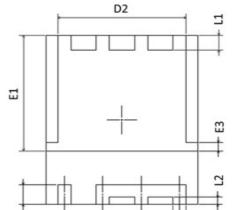


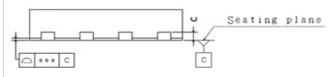
# Dimensions

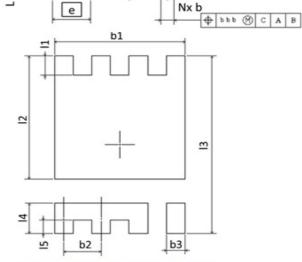
# DFN5060-8S











[reference pattern of soldering pads]

DIM	Milim	eters	Inc	hes
DIM	Min.	Max.	Min.	Max.
A	-	1.10	-	0.043
A1	_	0.05	-	0.002
С	0.2	03	0.0	800
Ь	0.34	0.54	0.013	0.021
D	4.90	5.10	0.193	0.201
D2	4.15	4.35	0.163	0.171
E	5.90	6.10	0.232	0.240
E1	4.00	4.20	0.157	0.165
E3	0.20	0.40	0.008	0.016
e	1.	27	0.0	50
L	0.60	0.80	0.024	0.031
L1	0.	.53 0.021		21
L2	0.	25	0.010	
N		1	8	
bbb	0.	0.10		04
ccc	0.	08	0.0	03

DIM	Milimeters	Inches
DIM	Nom.	Nom.
b1	4.45	0.175
b2	1.27	0.050
b3	0.64	0.025
11	0.72	0.028
12	4.58	0.180
13	6.60	0.260
14	1.13	0.044
15	0.50	0.020

Dimension in mm / inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	CL ACCIII	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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